

Absolute Maximum Ratings (@ 25° C)

Parameter	Min	Typ	Max	Units
Input Power Dissipation	-	-	150 ¹	mW
Input Control Current	-	-	50	mA
Peak (10ms)	-	-	1	A
Reverse Input Voltage	-	-	5	V
Total Power Dissipation	-	-	800 ²	mW
Isolation Voltage Input to Output	3750	-	-	V _{RMS}
Operational Temperature	-40	-	+85	°C
Storage Temperature	-40	-	+125	°C
Soldering Temperature	-	-	+260	°C
DIP Package	-	-	+220	°C
Flatpack/Surface Mount Pkg (10 Seconds Max.)	-	-	+220	°C

¹ Derate Linearly 1.33 mW/°C² Derate Linearly 6.67 mW/°C

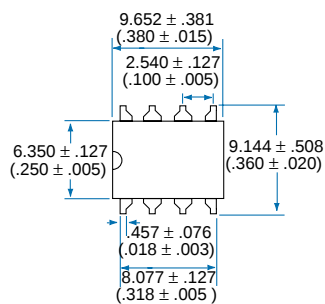
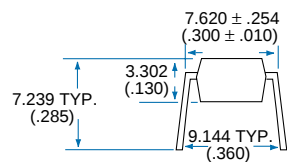
Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and effect its reliability.

Electrical Characteristics

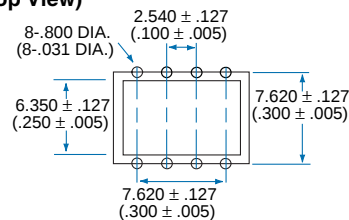
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics @ 25°C						
Load Voltage (Peak)	-	V _L	-	-	350	V
Load Current (Continuous)	-	I _L	-	-	120	mA
AC/DC Configuration	-	I _L	-	-	120	mA
Peak Load Current	10ms	I _{LPK}	-	-	350	mA
On-Resistance	-	-	-	-	-	-
AC/DC Configuration	I _L =120mA	R _{ON}	-	-	25	Ω
Off-State Leakage Current	V _L =350V	I _{LEAK}	-	-	1	μA
Switching Speeds	-	-	-	-	-	-
Turn-On	I _F =5mA, V _L =10V	T _{ON}	-	-	5	ms
Turn-Off	I _F =5mA, V _L =10V	T _{OFF}	-	-	5	ms
Output Capacitance	50V; f=1MHz	C _{OUT}	-	35	-	pF
Capacitance	-	-	-	-	-	-
Input to Output	-	-	-	3	-	pF
Input Characteristics @ 25°C						
Input Control Current	I _L =120mA	I _F	5	-	50	mA
Input Dropout Current	-	I _F	0.4	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Voltage	-	V _R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA

Mechanical Dimensions

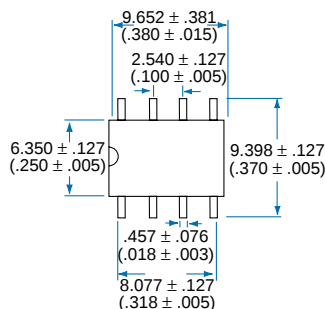
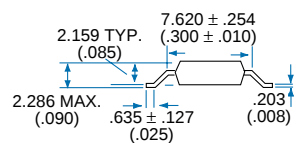
8 Pin DIP Through Hole (Standard)



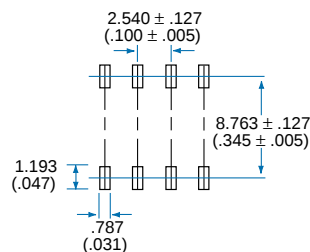
PC Board Pattern (Top View)



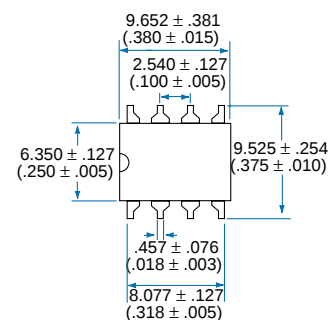
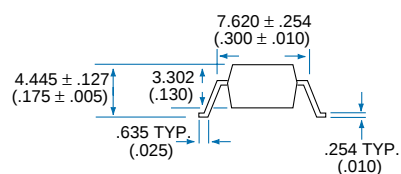
8 Pin Flatpack ("P" Suffix)



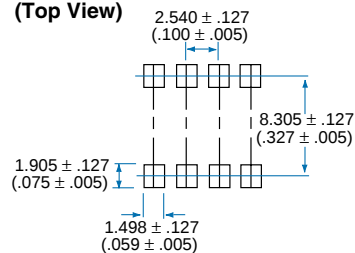
PC Board Pattern (Top View)



8 Pin DIP Surface Mount ("S" Suffix)



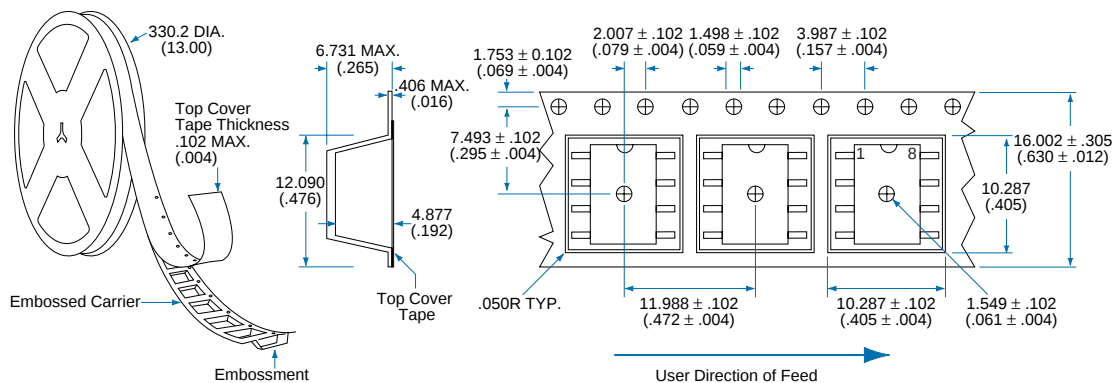
PC Board Pattern (Top View)



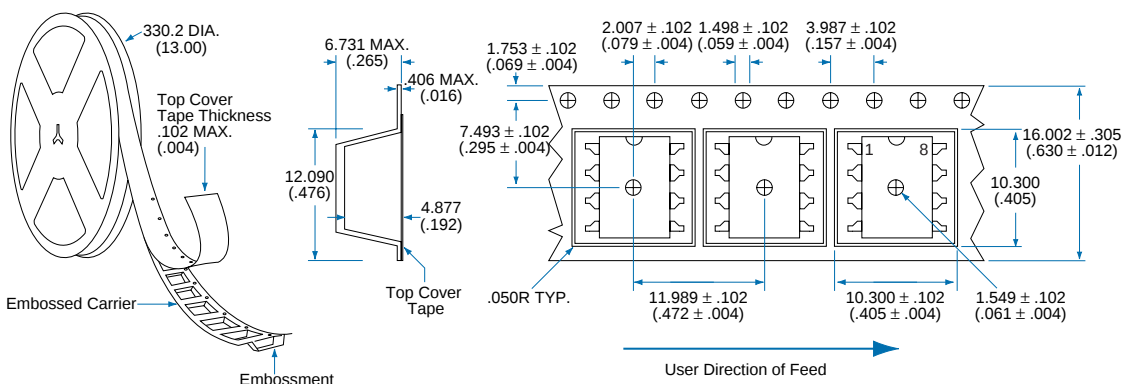
Dimensions
mm
(inches)

Mechanical Dimensions

Tape and Reel Packaging for 8 Pin Flatpack Package



Tape and Reel Packaging for 8 Pin Surface Mount Package



Dimensions
mm
(inches)



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